



## Product Change Notification / MFOL-28UNFU344

---

**Date:**

13-Dec-2022

**Product Category:**

Car Access, Wireless IC

**PCN Type:**

Manufacturing Change

**Notification Subject:**

CCB 5003 Final Notice: Qualification of FH-SC13/HR-5104 as new die attach material and G700LTD mold compound for selected Atmel ATA5577M1330C-UFQW and ATA5577M133DC-UFQW catalog part numbers (CPN) available in 2L XDFN (1.5x2x0.37mm) package at NSEB assembly site.

**Affected CPNs:**

[MFOL-28UNFU344\\_Affected\\_CPN\\_12132022.pdf](#)

[MFOL-28UNFU344\\_Affected\\_CPN\\_12132022.csv](#)

**Notification Text:**

**PCN Status:**Final Notification

**PCN Type:**Manufacturing Change

**Microchip Parts Affected:**Please open one of the files found in the Affected CPNs section.

Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

**Description of Change:**Qualification of FH-SC13/HR-5104 as new die attach material and G700LTD mold compound for selected Atmel ATA5577M1330C-UFQW and ATA5577M133DC-UFQW catalog part numbers (CPN) available in 2L XDFN (1.5x2x0.37mm) package at NSEB assembly site.

**Pre and Post Change Summary:**

	Pre Change	Post Change
Assembly Site	UTAC Thai Limited (UTL-1) LTD.  (NSEB)	UTAC Thai Limited (UTL-1) LTD.  (NSEB)
Wire Material	Au	Au
Die Attach Material	HS-261W	FH-SC13/HR-5104
Molding Compound Material	CEL-8240HF10G	G700LTD
Lead-Frame Material	EFTEC-64T	EFTEC-64T
Lead-Frame Paddle Size	50x31 mils	50x31 mils
DAP Surface Prep	Copper (Ag custom)	Copper (Ag custom)

**Impacts to Data Sheet:**None

**Change Impact:**None

**Reason for Change:**To improve productivity and on-time delivery performance by qualifying FH-SC13/HR-5104 as new die attach material and G700LTD mold compound at NSEB assembly site.

**Change Implementation Status:**In Progress

**Estimated First Ship Date:**January 15, 2023 (date code: 2303)

Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

**Time Table Summary:**

	March 2022					>	December 2022					January 2023				
Workweek	10	11	12	13	14		49	50	51	52	53	01	02	03	04	05
Initial PCN Issue Date		x														
Qual Report Availability									x							
Final PCN Issue Date									x							
Estimated Implementation Date														x		

**Method to Identify Change:**Traceability code

**Qualification Report:**

Please open the attachments included with this PCN labeled as PCN\_#\_Qual\_Report.

**Revision History:**

**March 09, 2022:** Issued initial notification.

**December 13, 2022:** Issued final notification. Attached the qualification report and added estimated first ship date by January 15, 2023.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

**Attachments:**

[PCN\\_MFOL-28UNFU344\\_Qual\\_Report.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

**Terms and Conditions:**

If you wish to receive Microchip PCNs via email please register for our PCN email service at our [PCN home page](#) select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the [PCN FAQ](#) section.

If you wish to change your PCN profile, including opt out, please go to the [PCN home page](#) select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

---

MFOL-28UNFU344 - CCB 5003 Final Notice: Qualification of FH-SC13/HR-5104 as new die attach material and G700LTD mold compound for selected Atmel ATA5577M1330C-UFQW and ATA5577M133DC-UFQW catalog part numbers (CPN) available in 2L XDFN (1.5x2x0.37mm) package at NSEB assembly site.

---

Affected Catalog Part Numbers (CPN)

ATA5577M1330C-UFQW

ATA5577M133DC-UFQW